## **Specification of Thermoelectric Module**

**TEHC1-08320P** 

### **Description**

The 83 couples, 44 mm  $\times$  38/42 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74  $^{\circ}$ C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

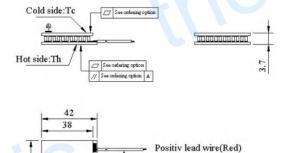
## **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### **Performance Specification Sheet**

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	10.9	11.8	Voltage applied to the module at DT <sub>max</sub>
I <sub>max(</sub> amps)	19.6	19.6	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	136.8	149.3	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	0.44	0.46	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters





18 AWG Leads, Teflon insulated
Negative lead wire(Black)

Suffix	Thickness	Flatness/	Lead wire length(mm)	
	(mm)	Parallelism (mm)	Standard/Optional length	
TF	0:3.7±0.1	0:0.1/0.1	125±1/Specify	
TF	1:3.7±0.05	1:0.05/0.05	125±1/Specify	
Eg. TF01: Thickness 3.7±0.1(mm) and Flatness 0.05/0.05(mm)				

## **Manufacturing Options**

Α.	Solder
/A.	Soluci.

#### B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

### C. Ceramics:

### **D.** Ceramics Surface Options:

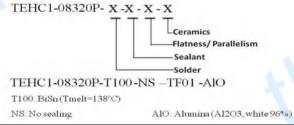
1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

## Naming for the Module



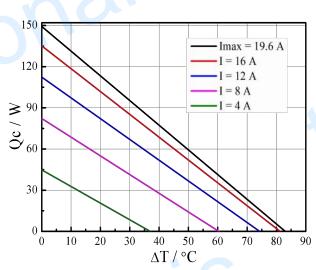
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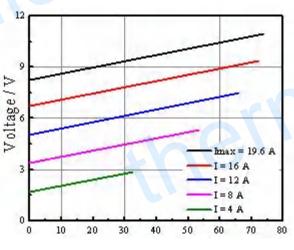
### Performance Curves at Th=27 °C

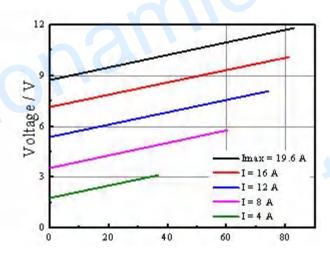
#### 140 Imax = 19.6 A120 I = 16 AI = 12 A100 I = 8 AØ 60 ⊗ 60 I = 4 A40 20 0 30 70 10 20 60 80 0 $\Delta T / {}^{\circ}C$

### Performance Curves at Th=50 °C

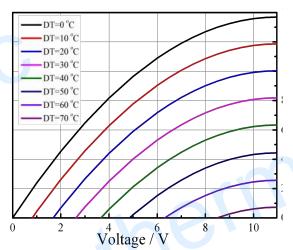


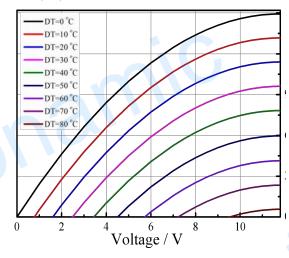
Standard Performance Graph Qc= f(DT)





Standard Performance Graph  $V = f(\Delta T)$ 





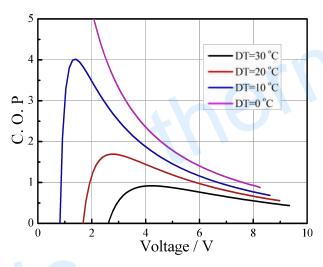
Standard Performance Graph Qc = f(V)

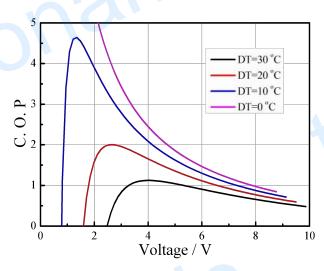
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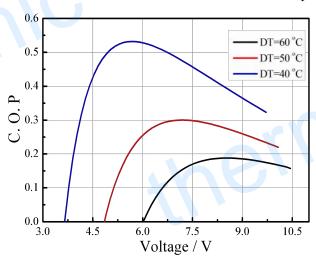
### Performance Curves at Th=27 °C

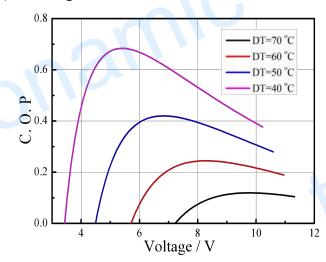
### Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

## **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC